



650V Super-junction Power MOSFET

Description

650V Super-junction Power MOSFET

Super-junction power MOSFET is a revolutionary technology for high voltage power MOSFETs, designed according to the SJ principle. The deep trench SJ MOSFET provide an extremely low switching, communication and conduction losses device with highest robustness make especially resonant switching applications more reliable, more efficient, lighter and cooler, designed by Wuxi Unigroup Microelectronics Company.

Features

- Very low FOM $R_{DS(on)} \times Q_g$
- 100% avalanche tested
- Easy to use/drive
- RoHS compliant

Applications

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)
- Charger

TO-220F



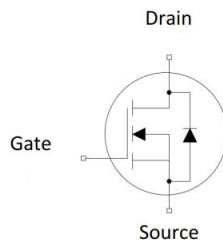
TO-263



TO-252



Drain



Device Marking and Package Information

Device	Package	Marking
TPA65R520D	TO-220F	65R520D
TPB65R520D	TO-263	65R520D
TPD65R520D	TO-252	65R520D

Key Performance Parameters

Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	700	V
$R_{DS(on),max}$	0.52	Ω
$Q_{g,typ}$	12.5	nC
I_D	7	A
$I_{D,pulse}$	21	A
$E_{oss} @ 400V$	1.66	μJ

**Absolute Maximum Ratings** $T_C = 25^\circ\text{C}$, unless otherwise noted

Parameter		Symbol	Values	Unit
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	7	A
	$T_C = 100^\circ\text{C}$		4	
Pulsed Drain Current	(note1)	$I_{D,\text{pulse}}$	21	A
Gate-Source Voltage		V_{GSS}	$\pm 30\text{V}$	V
Single Pulse Avalanche Energy	(note2)	E_{AS}	45	mJ
Repetitive Avalanche Energy	(note2)	E_{AR}	0.28	mJ
Avalanche Current		I_{AR}	3	A
MOSFET dv/dt Ruggedness, $V_{DS} = 0\ldots 480\text{V}$		dv/dt	50	V/ns
Power Dissipation For TO-220F		P_D	28	W
Power Dissipation For TO-263,TO-252			62.5	
Continuous Diode Forward Current		I_S	7	A
Diode Pulsed Current	(note1)	$I_{S,\text{pulse}}$	21	
Reverse Diode dv/dt	(note3)	dv/dt	5	V/ns
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55~+150	°C

Thermal Resistance For TO-220F

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R_{thJC}	4.5	°C/W
Thermal Resistance, Junction-to-Ambient	R_{thJA}	80	

Thermal Resistance For TO-263,TO-252

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R_{thJC}	2	°C/W
Thermal Resistance, Junction-to-Ambient	R_{thJA}	62	


Electrical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	650	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 650\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 25^\circ\text{C}$	--	--	1	μA
		$V_{\text{DS}} = 650\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 150^\circ\text{C}$	--	--	100	
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}} = \pm 30\text{V}$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2.5	--	4.0	V
Drain-Source On-State-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 3\text{A}$	--	0.44	0.52	Ω
Dynamic Characteristics						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 100\text{V}, f = 1.0\text{MHz}$	--	564	--	pF
Output Capacitance	C_{oss}		--	22	--	
Reverse Transfer Capacitance	C_{rss}		--	0.5	--	
Total Gate Charge	Q_g	$V_{\text{DD}} = 520\text{V}, I_D = 7\text{A}, V_{\text{GS}} = 10\text{V}$	--	12.5	--	nC
Gate-Source Charge	Q_{gs}		--	5	--	
Gate-Drain Charge	Q_{gd}		--	3.2	--	
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 400\text{V}, I_D = 7\text{A}, R_G = 25\Omega$	--	52	--	ns
Turn-on Rise Time	t_r		--	62	--	
Turn-off Delay Time	$t_{\text{d}(\text{off})}$		--	84	--	
Turn-off Fall Time	t_f		--	50	--	
Drain-Source Body Diode Characteristics						
Body Diode Forward Voltage	V_{SD}	$T_J = 25^\circ\text{C} I_{\text{SD}} = 7\text{A}, V_{\text{GS}} = 0\text{V}$	--	0.9	1.2	V
Reverse Recovery Time	t_{rr}	$V_R = 400\text{V}, I_S = 3\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$	--	200	--	ns
Reverse Recovery Charge	Q_{rr}		--	1.6	--	
Peak Reverse Recovery Current	I_{rrm}		--	3.2	--	

Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $I_D = 10\text{A}, V_{\text{DD}} = 50\text{V}, R_G = 25\Omega$, Starting $T_J = 25^\circ\text{C}$
3. Identical low side and high side switch with identical R_G



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

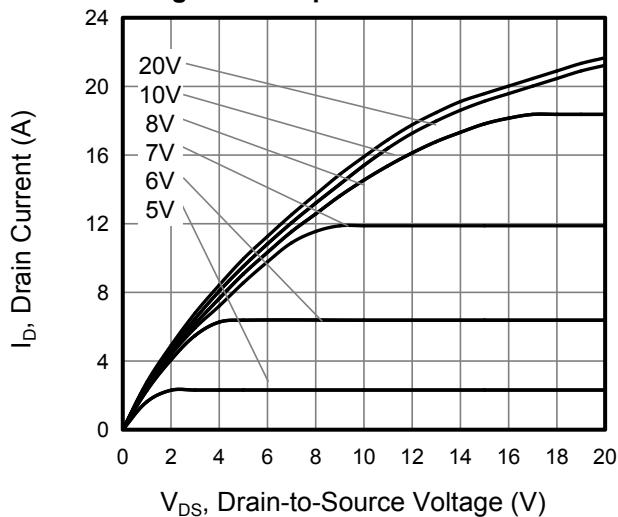


Figure 2. Transfer Characteristics

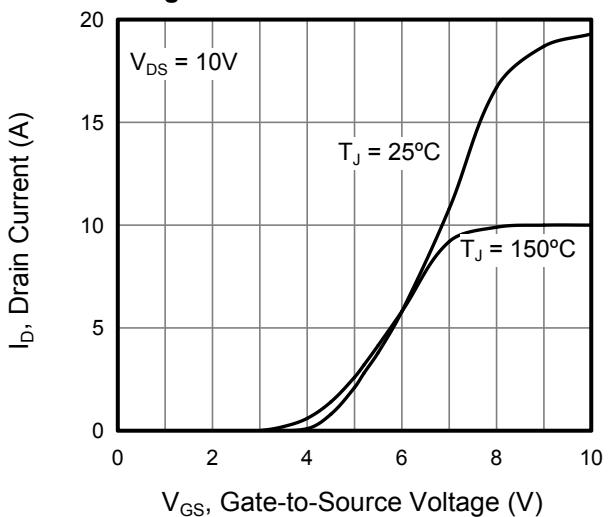


Figure 3 . On-Resistance vs. Drain Current

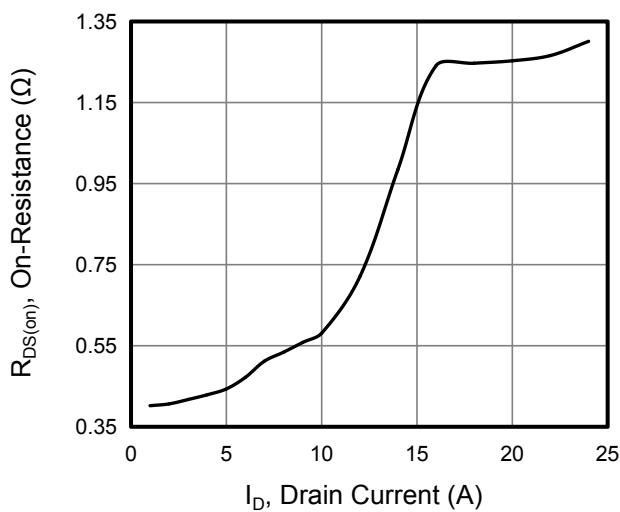


Figure 4. Capacitance

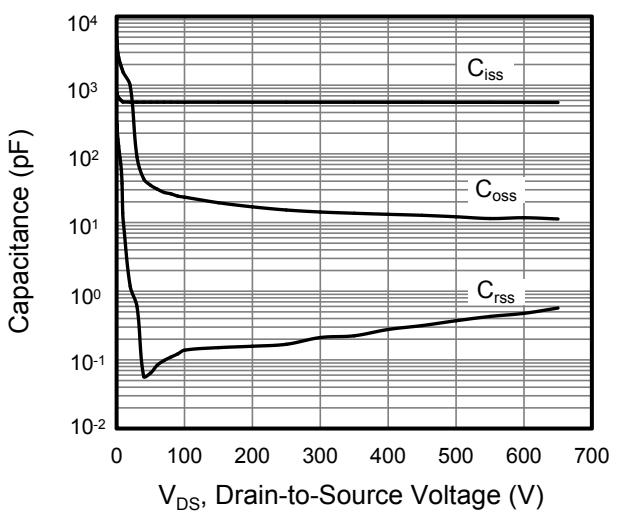


Figure 5. Gate Charge

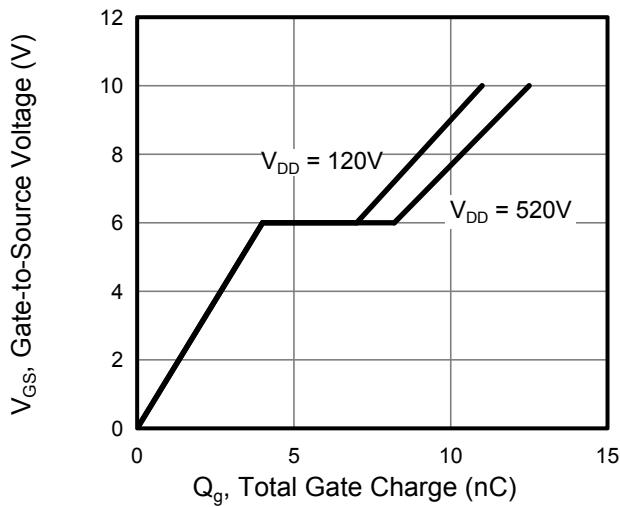


Figure 6. Body Diode Forward Voltage

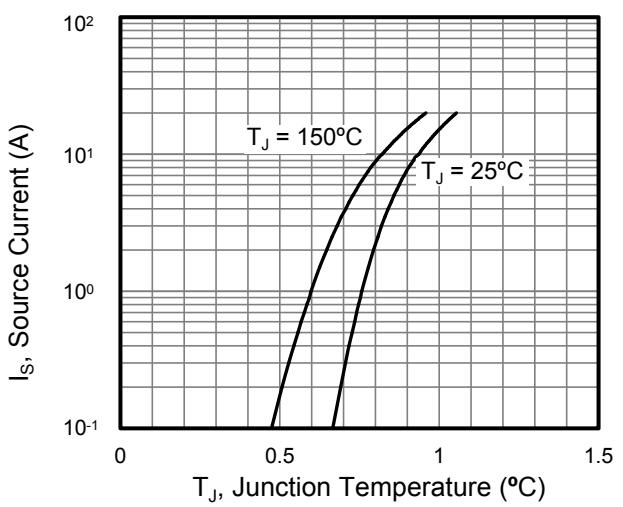
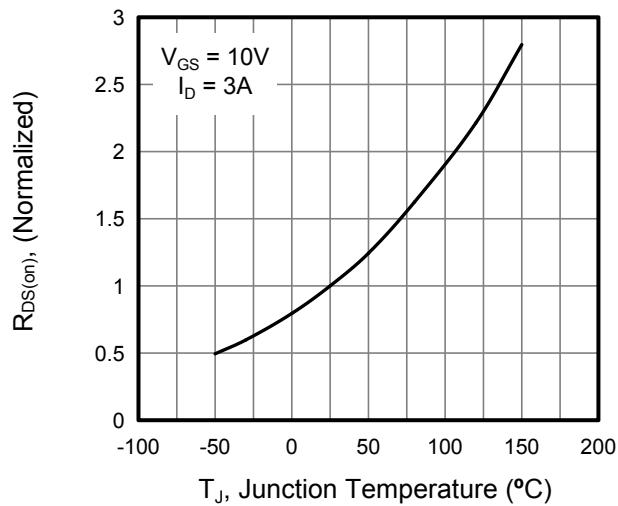
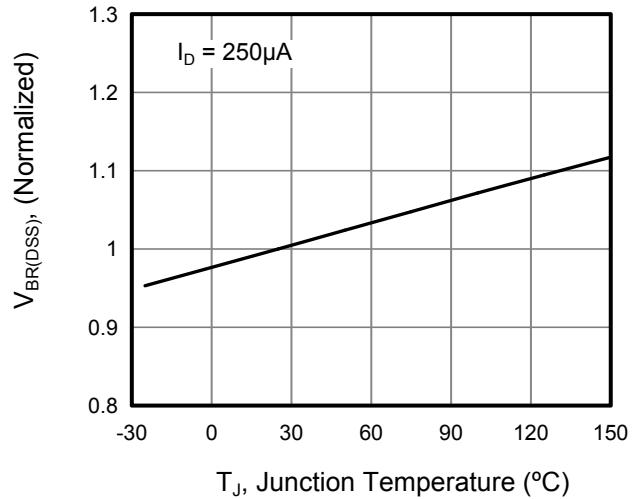
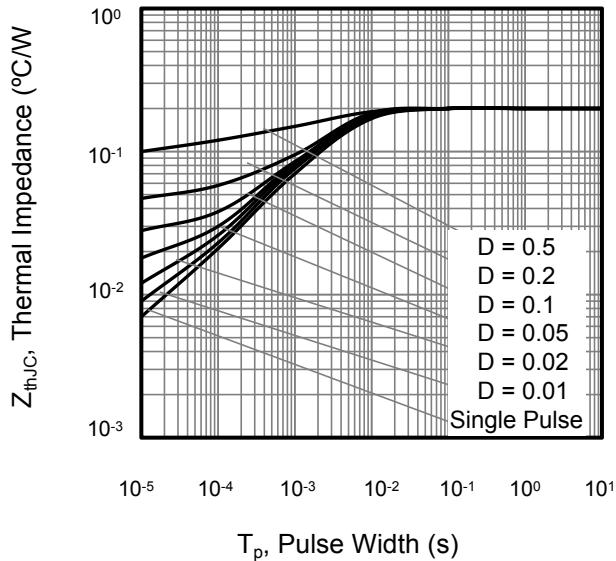
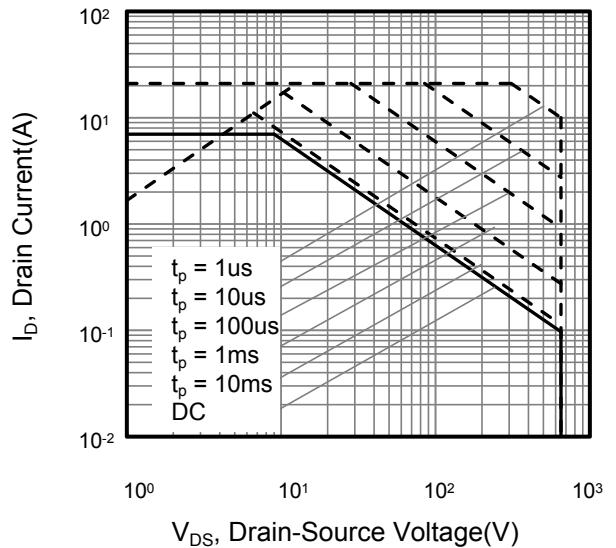
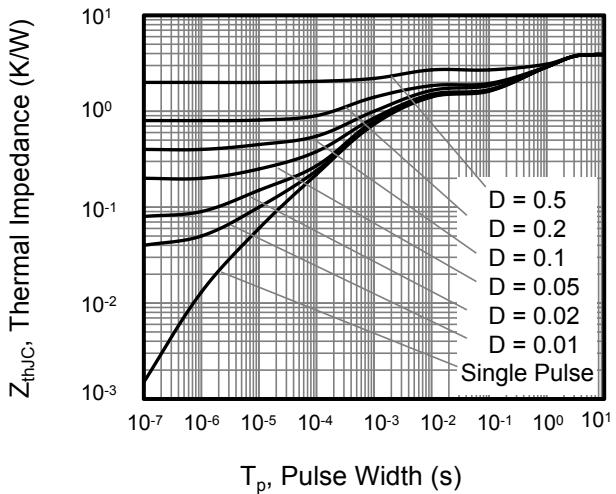
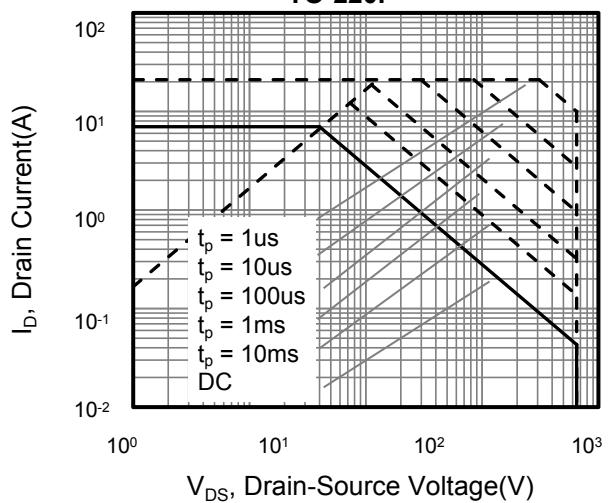
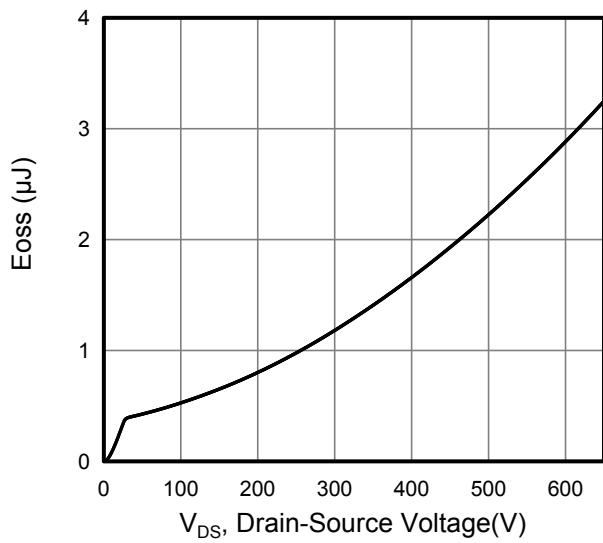
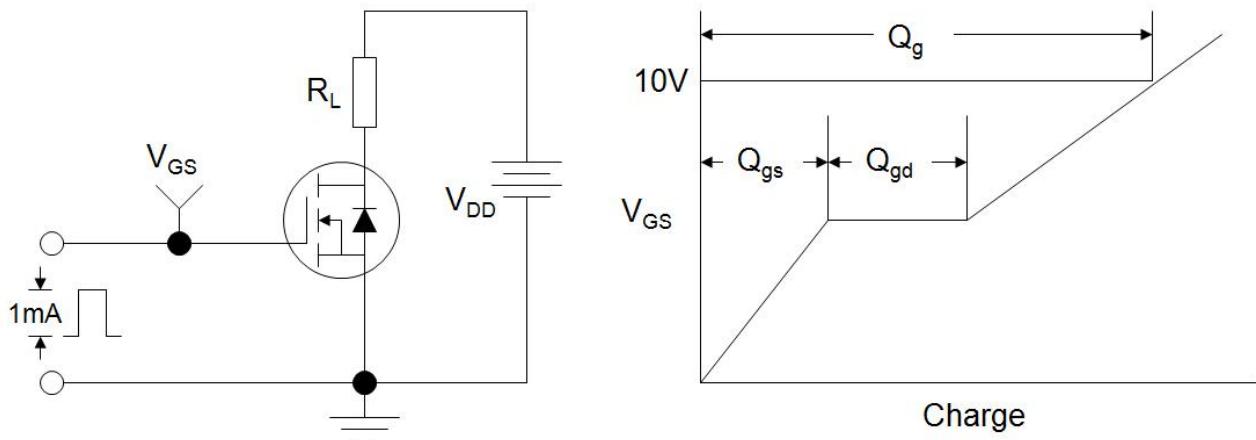
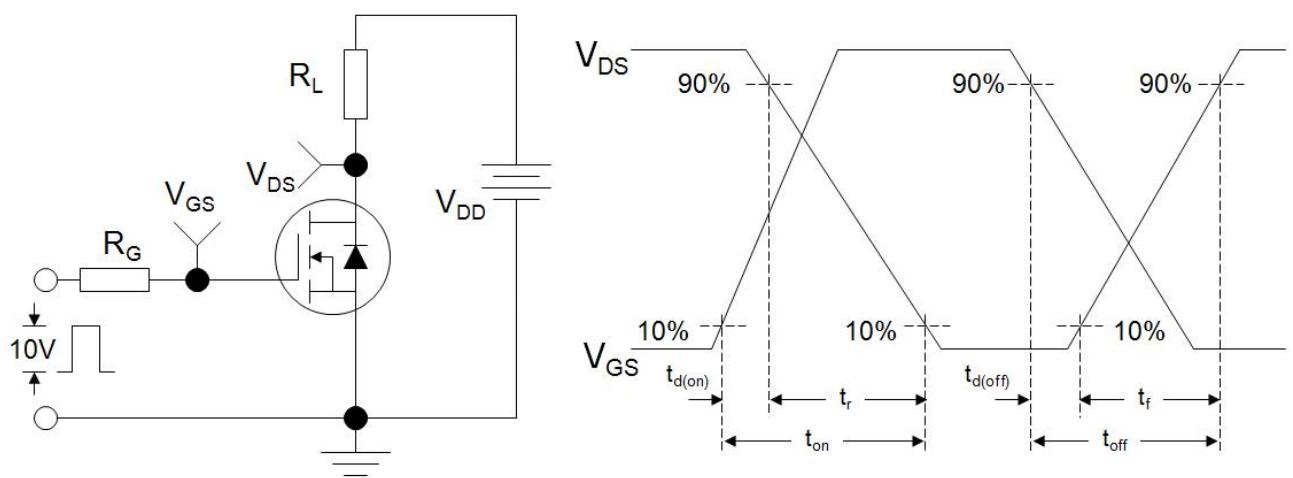
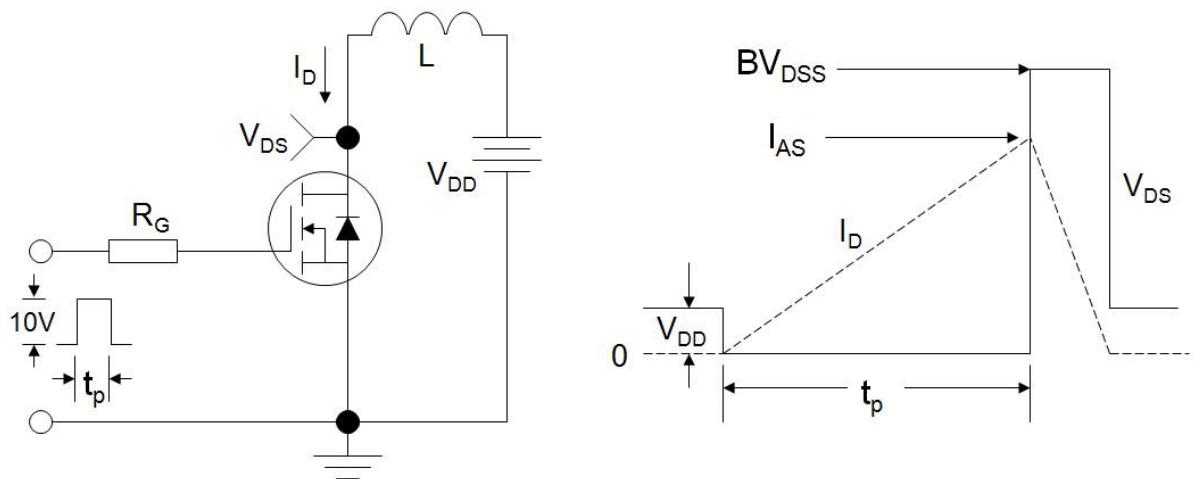


Figure 7. On-Resistance vs. Temperature

Figure 8. Breakdown voltage vs. Junction Temperature

Figure9 . Transient Thermal Impedance For TO-263/TO-252

Figure 10. Safe Operation Area For TO-263/TO-252

Figure 11. Transient Thermal Impedance For TO-220F

Figure 12. Safe Operation Area For TO-220F


Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

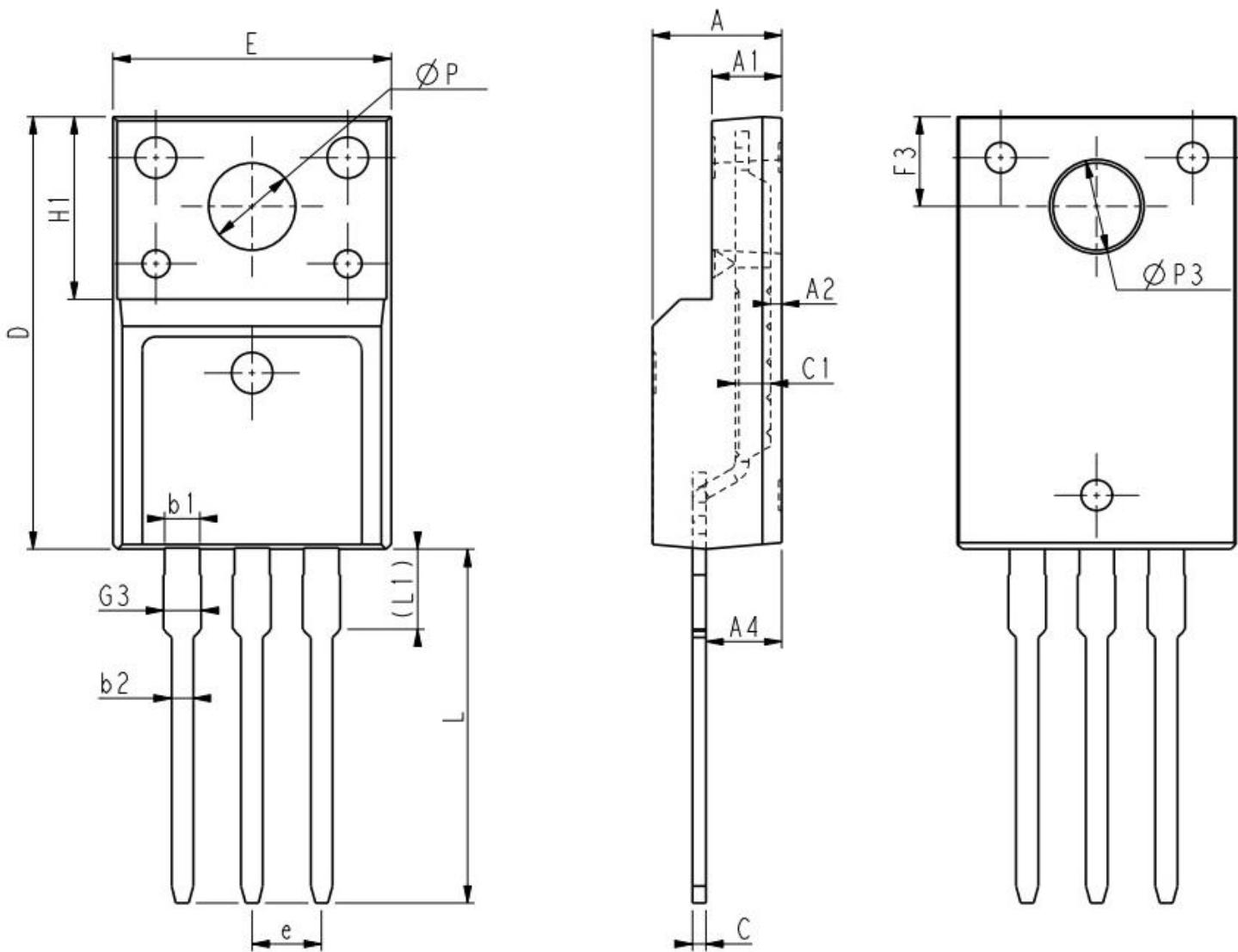
Figure 13. Typ. Coss Stored Energy



**Figure A: Gate Charge Test Circuit and Waveform****Figure B: Resistive Switching Test Circuit and Waveform****Figure C: Unclamped Inductive Switching Test Circuit and Waveform**



TO-220F (封装厂 H)

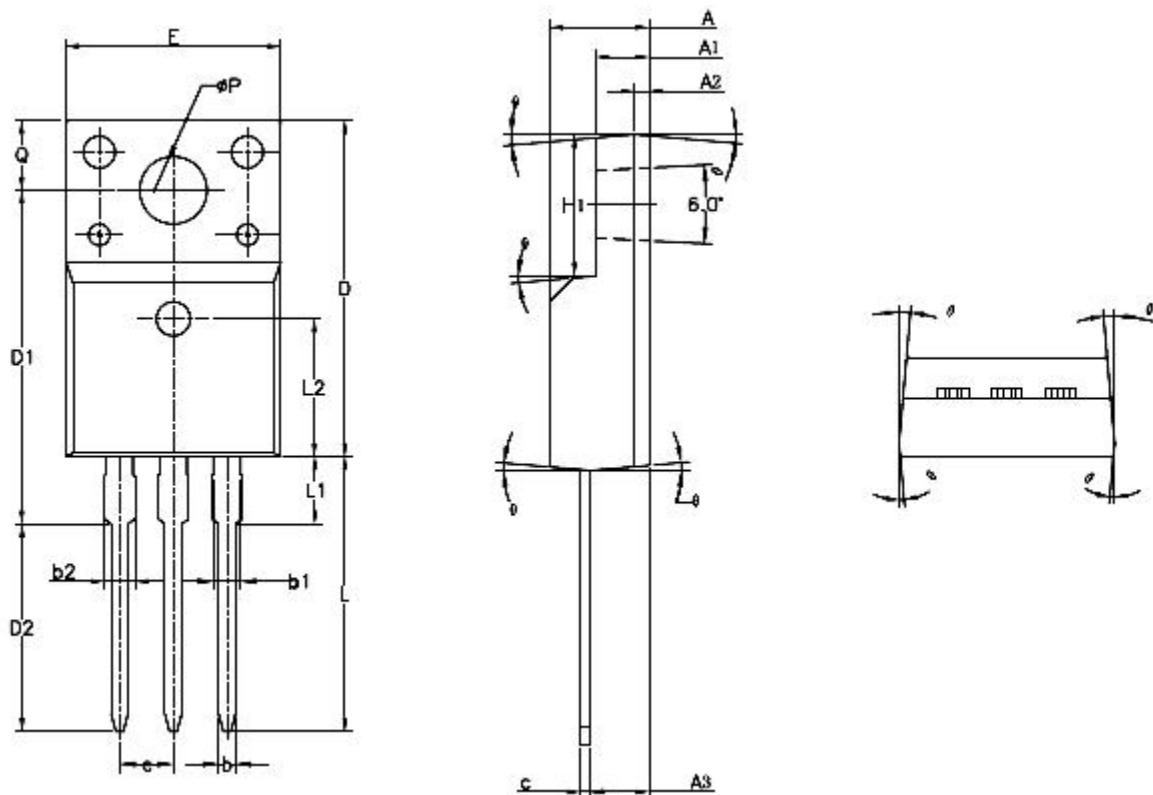


Unit:mm			
Symbol	Min.	Nom	Max.
E	9.96	10.16	10.36
A	4.50	4.70	4.90
A1	2.34	2.54	2.74
A2	0.30	0.45	0.60
A4	2.56	2.76	2.96
c	0.40	0.50	0.65
c1	1.20	1.30	1.35
D	15.57	15.87	16.17
H1	6.70REF		

Unit:mm			
Symbol	Min.	Nom	Max.
e	2.54BSC		
L	12.68	12.98	13.28
L1	2.93	3.03	3.13
φP	3.03	3.18	3.38
φP3	3.15	3.45	3.65
F3	3.15	3.30	3.45
G3	1.25	1.35	1.55
b1	1.18	1.28	1.43
b2	0.70	0.80	0.95



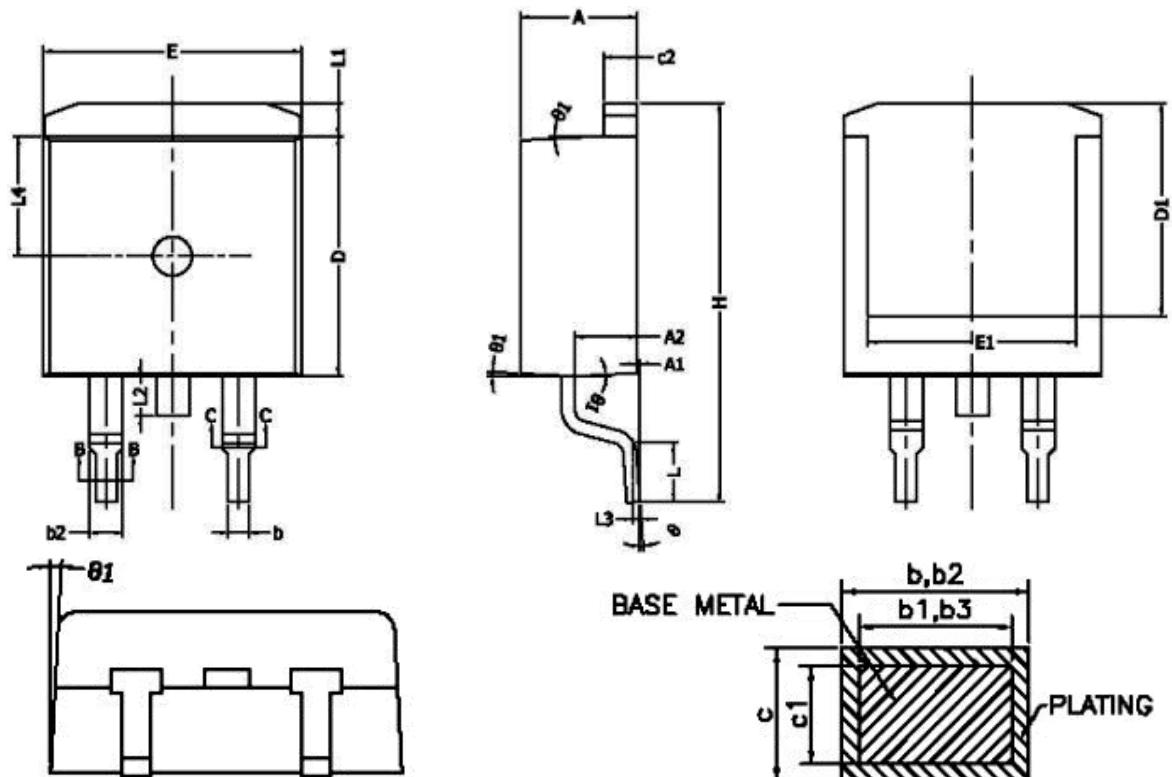
TO-220F (封装厂 I)



SYMBOL	MIN	NOM	MAX
A	4.50	4.70	4.83
A1	2.34	2.54	2.74
A2	0.70 REF		
A3	2.56	2.76	2.93
b	0.70	—	0.90
b1	1.18	—	1.38
b2	—	—	1.47
c	0.45	0.50	0.60
D	15.67	15.87	16.07
D1	15.55	15.75	15.95
D2	9.60	9.80	10.0
E	9.96	10.16	10.36
e	2.54BSC		
H1	6.48	6.68	6.88
L	12.68	12.98	13.28
L1	—	—	3.50
L2	6.50REF		
øP	3.08	3.18	3.28
Q	3.20	—	3.40
θ 1	1°	3°	5°



TO-263 (封装厂 I)

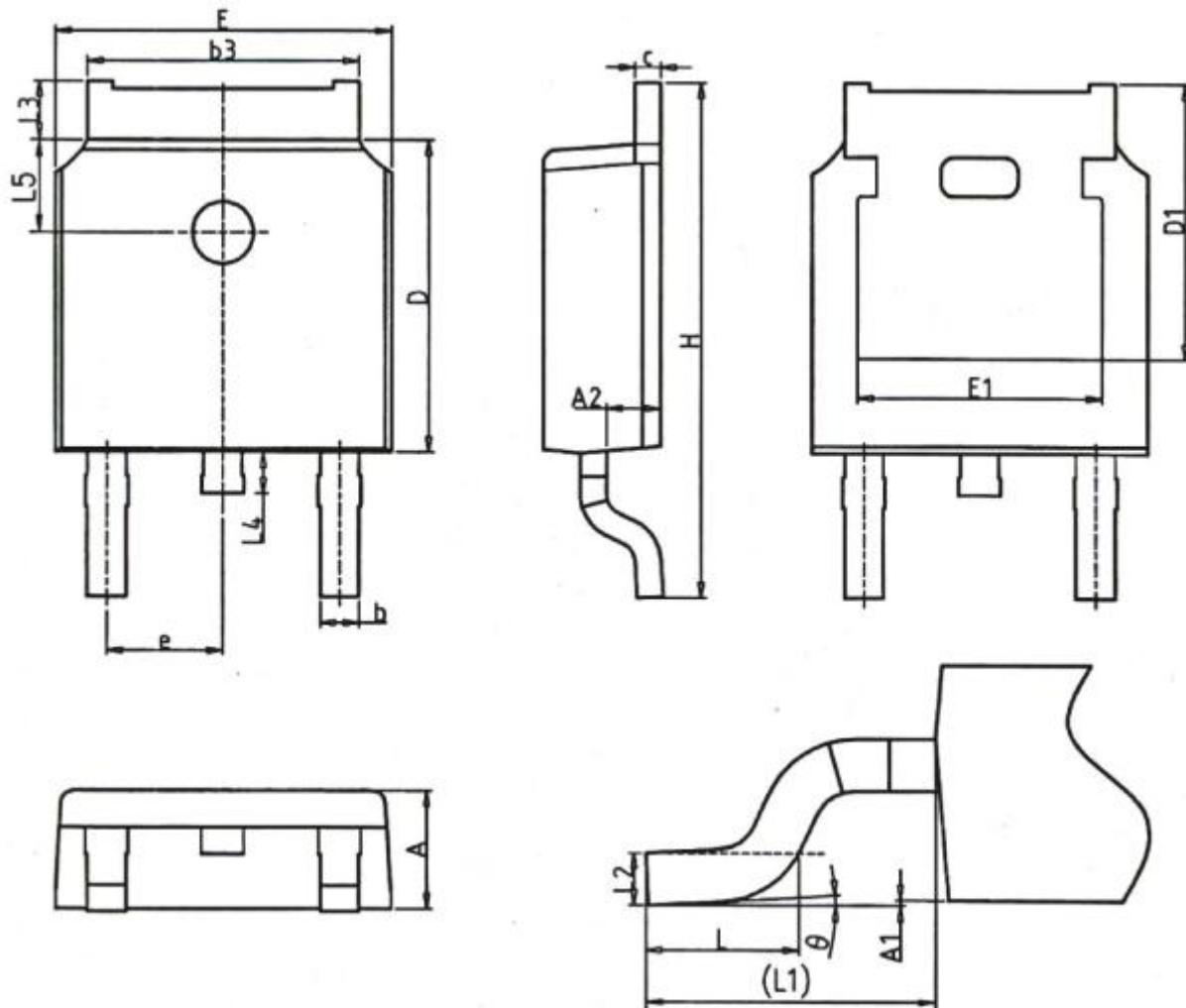


SECTION B-B&C-C

SYMBOL	MIN	NOM	MAX
A	4.40	4.50	4.60
A1	0	0.10	0.25
A2	2.20	2.40	2.60
b	0.76	--	0.89
b1	0.75	0.80	0.85
b2	1.23	--	1.37
b3	1.22	1.27	1.32
c	0.47	--	0.60
c1	0.46	0.51	0.56
c2	1.25	1.30	1.35
D	9.10	9.20	9.30
D1	8.00	--	--
E	9.80	9.90	10.00
E1	7.80	--	--
e	2.54 BSC		
H	14.90	15.30	15.70
L	2.00	2.30	2.60
L1	1.17	1.27	1.40
L2	--	--	1.75
L3	0.25BSC		
L4	4.60 REF		
θ	0°	--	8°
θ1	1°	3°	5°



TO-252 (封装厂 H)

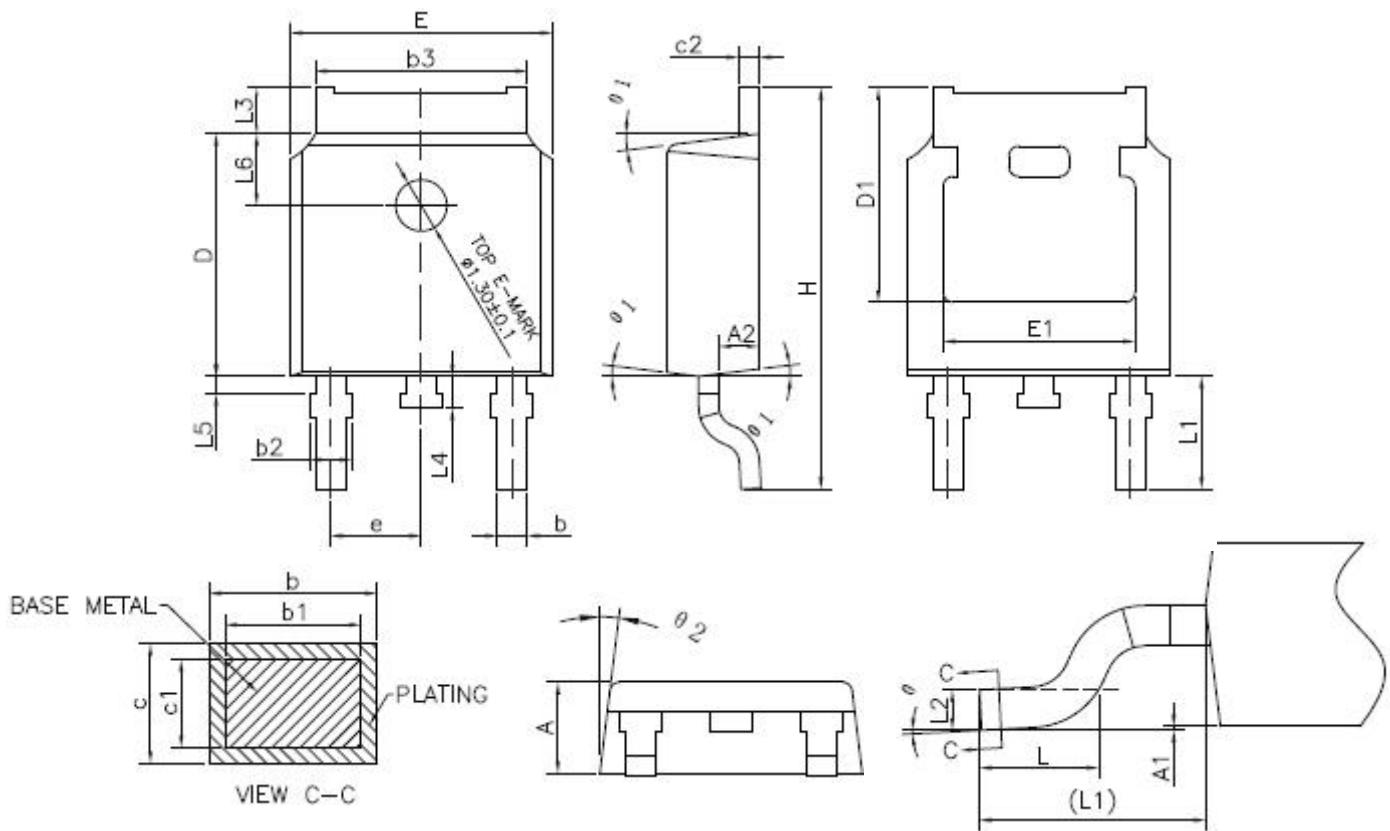


Unit:mm			
Symbol	Min.	Nom	Max.
A	2.20	2.30	2.38
A1	0.00	-	0.20
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b3	5.20	5.33	546
c	0.43	0.53	0.61
D	5.98	6.10	6.22
D1	5.30 REF		
E	6.40	6.60	6.73
E1	4.63	-	-

Unit:mm			
Symbol	Min.	Nom	Max.
e	2.286 BSC		
H	9.40	10.10	10.50
L	1.38	1.50	1.75
L1	2.90 REF		
L2	0.51 BSC		
L3	0.88	-	1.28
L4	0.50	-	1.00
L5	1.65	1.80	1.95
θ	0°	-	8°



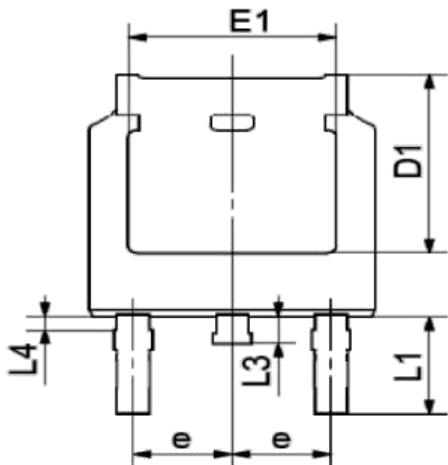
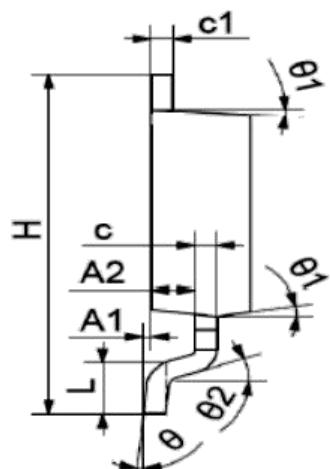
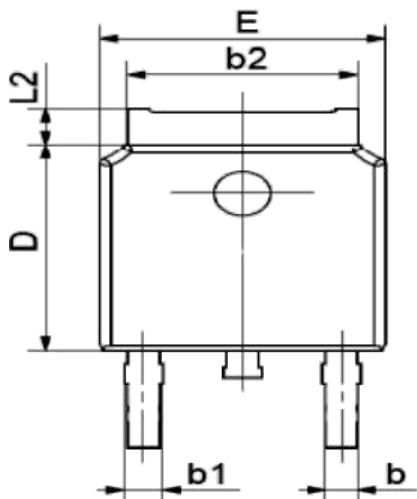
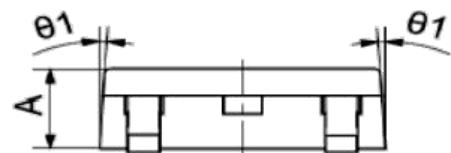
TO-252 (封装厂 I)



SYMBOL	MIN	NOM	MAX
A	2,20	2,30	2,38
A1	0	—	0,10
A2	0,90	1,01	1,10
b	0,72	—	0,85
b1	0,71	0,76	0,81
b2	0,72	—	0,90
b3	5,13	5,33	5,46
c	0,47	—	0,60
c1	0,46	0,51	0,56
c2	0,47	—	0,60
D	6,00	6,10	6,20
D1	5,25	—	—
E	6,50	6,60	6,70
E1	4,70	—	—
e	2,186	2,286	2,386
H	9,80	10,10	10,40
L	1,40	1,50	1,70
L1	2,90 REF		
L2	0,508 BSC		
L3	0,90	—	1,25
L4	0,60	0,80	1,00
L5	0,15	—	0,75
L6	1,80 REF		
θ	0°	—	8°
θ1	5°	7°	9°
θ2	5°	7°	9°



TO-252 (封装厂 E)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.10	2.50	0.083	0.098
A1	0	0.15	0.000	0.006
A2	0.76	1.36	0.030	0.054
b	0.61	0.85	0.024	0.033
b1	0.71	0.91	0.028	0.036
b2	5.04	5.64	0.198	0.222
c	0.508 TYP.		0.02 TYP.	
c1	0.508 TYP.		0.02 TYP.	
D	5.8	6.3	0.228	0.248
D1	5	5.6	0.197	0.220
E	6.3	6.9	0.248	0.272
E1	4.55	5.15	0.179	0.203
e	2.286 TYP.		0.09 TYP.	
H	9.65	10.4	0.380	0.409
L	1.4	1.7	0.055	0.067
L1	2.90 REF.		0.114 REF.	
L2	0.75	1.35	0.030	0.053
L3	0.6	1.2	0.024	0.047
θ	0°	10°	0°	10°
θ1	5°	9°	5°	9°
θ2	25° REF.		25° REF.	



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